

RESPONSE TO FINAL OFFICE ACTION
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when executed by a processor, cause the processor to control a semiconductor wafer processing system to perform the steps of:

supplying a cleaning agent to a chamber after a substrate is removed therefrom;

pumping said cleaning agent from the chamber through a pumping system having a turbomolecular pump and roughing pump coupled in parallel;

at least partially opening a valve coupled between said chamber and the turbomolecular pump of the pumping system; and

drawing at least a portion of said cleaning agent through said turbomolecular pump.

B) Please add the following new claims:

–16. (New) The computer-readable medium of claim 6 further comprising:
drawing a portion of said cleaning agent through the roughing pump.

17. (New) The computer-readable medium of claim 6, wherein the step of at least partially opening the valve coupled between the chamber and the turbomolecular pump further comprises:
partially opening the valve.

18. (New) A computer-readable medium having stored thereon a plurality of instructions, the plurality of instructions including instructions which, when executed by a processor, cause the processor to control a semiconductor wafer processing system to perform the steps of:

supplying a cleaning agent to a deposition chamber;

pumping said cleaning agent from the deposition chamber through a pumping system having a turbomolecular pump and roughing pump coupled in parallel;

partially opening a valve coupled between said deposition chamber and the turbomolecular pump of the pumping system; and